Size 20161A

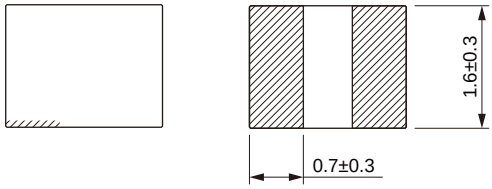
FEATURES

- High current, low DCR,high e ciency.
- Very low acous c noise and very low leakage flux noise.
- AEC-Q200 qualified
- 100% Lead(Pb)-Free and RoHS compliant.
- Opera ng temperature: -55 to +155 °C (including self-temperature rise)
- Quan ty: 3000PCS

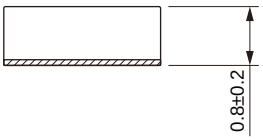
APPLICATION

- ADAS
- Headlamps, tail lamps and interior ligh ng
- HVAC
- Doors, window li and seat control
- Audio subsystem
- Digital instrument cluster
- In-Vehicle Infotainment and naviga on

Dimensions: [mm]



Land Pattern: [mm]



Electrical Properties:

Part No	Inductance @ 100KHz/1V (µH)	Tolerance	Temperature Rise Current Typ. (A)	Temperature Rise Current Max. (A)	Satura on Current Typ. (A)	Satura on Current Max. (A)	DC Resistance Typ. (mΩ)	DC Resistance Max. (mΩ)
MDTA20161A-R24M	0.24	±20%	6.8	6.2	7.3	7.0	15	18
MDTA20161A-R33M	0.33	±20%	6.5	6.0	7.0	6.5	17	20
MDTA20161A-R47M	0.47	±20%	6.0	5.5	6.3	5.5	19	22
MDTA20161A-R68M	0.68	±20%	5.0	4.5	5.2	4.7	24	31
MDTA20161A-1R0M	1.00	±20%	4.0	3.7	4.8	4.2	38	46

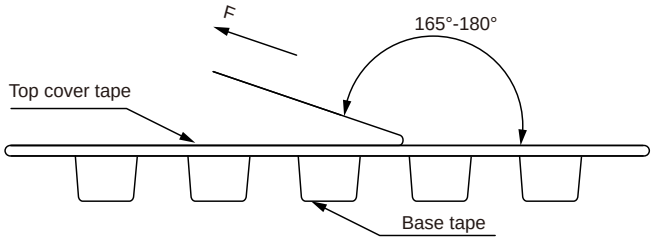
Soldering Reflow:

Packaging Information:

Tape Dimension:

Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
MDTA20161A	1.9 ± 0.1	2.3 ± 0.1	1.5 ± 0.1	4.0 ± 0.1	4 ± 0.1	8.0 ± 0.3	1.2 ± 0.1	1.75 ± 0.1	0.25 ± 0.05

Peel force of top cover tape:



The peel force of top cover tape shall be between 0.1 to 0.98 N

Reel Dimension：[mm]

Cautions and Warnings:

Storage Conditions：

- The storage period is within 12 months after the completion of production. Be sure to follow the storage conditions (temperature: -5 to 35°C, humidity: 75% RH Max).If the storage period elapses, the soldering of the terminal electrodes may deteriorate.The warranty period is one year.
- Product should not be exposed to environment with high temperature, high humidity, dust, corrosive gas and etc.
- Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- Please always handle products carefully to prevent any damage caused by dropping down or inappropriate removing.

Operation Instructions:

- Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
- Before soldering, be sure to preheat components.The preheating temperature should be set so that the temperature difference between the solder temperature and chip temperature does not exceed 150°C.
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